

**Version with Markings to Show Changes Made****In the Claims:**

Claims 1, 13, 16, 20, 26, 31 and 32 have been amended as follows.

1. (Three Times Amended) A multi-chamber system of an etching facility for manufacturing semiconductor devices comprising:

- a cassette stage for mounting a cassette having wafers stacked thereon;
- a transfer path adjacent to the cassette stage for providing space for transportation of wafers, the transfer path being at atmospheric pressure;
- a plurality of processing chambers aligned with the transfer path;
- a transfer mechanism installed in the transfer path for loading and unloading the wafers stacked on the cassette stage; and
- at least one load lock chamber, [coupled between the plurality of processing chambers and the transfer path,] each said load lock chamber being directly connected to at one side of at least one of the processing chambers and serving as a stand-by area for the wafers.

13. (Amended) The multi-chamber system of an etching facility for manufacturing semiconductor devices according to claim 11, wherein the transfer arm is provided with a vacuum line so as to [vacuum-absorb] vacuum-suction the wafers.

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16. (Amended) The multi-chamber system of an etching facility for manufacturing semiconductor devices according to claim [11] 12, wherein the vertical driving part comprises a motor or a pneumatic cylinder.

20. (Four Time Amended) A multi-chamber system of an etching facility for manufacturing semiconductor devices comprising:

a cassette stage for mounting a cassette having wafers stacked thereon;

a transfer path adjacent to the cassette stage for providing space for transportation of wafers, the transfer path being at atmospheric pressure and having a width slightly larger than a diameter of the wafers;

a plurality of processing chambers aligned in a plurality of layers parallel to and [beside] adjoining the transfer path;

a transfer mechanism capable of vertical/horizontal reciprocal movement installed in the transfer path for loading and unloading the wafers stacked on the cassette stage; and

a load lock chamber directly connected to one side of the processing chambers, the load lock chamber serving as a stand-by area for the wafers.

26. (Amended) The multi-chamber system of an etching facility for manufacturing semiconductor devices according to claim 20, wherein the transfer mechanism comprises:

1

a transfer arm having a vacuum line so as to selectively [vacuum-absorb]
vacuum-suction the wafers;

a transfer robot for loading and unloading the wafers into the processing chamber by moving the transfer arm;

a vertical driving part for moving the transfer robot vertically;

a horizontal driving part for moving the transfer robot horizontally; and

a controller for controlling the transfer robot, the vertical driving part, and the horizontal driving part by applying control signals thereto.

31. (Three Times Amended) A multi-chamber system of an etching facility for manufacturing semiconductor devices comprising:

a first cassette stage for mounting a cassette having unprocessed wafers stacked thereon;

a transfer path adjacent to the first cassette stage that provides space for transportation of wafers, the transfer path being at atmospheric pressure and having a width slightly larger than a diameter of the wafers;

a plurality of processing chambers arranged in multi-layers and aligned in parallel [beside] adjoining the transfer path;

a transfer mechanism capable of vertical/horizontal reciprocal movement installed in the transfer path for loading and unloading the wafers stacked on the first cassette stage; and

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a second cassette stage placed opposite to the first cassette stage and mounting thereon a cassette having processed wafers stacked thereon.

32. (Amended) The multi-chamber system of an etching facility for manufacturing semiconductor devices according to claim 31, wherein the transfer mechanism comprises:

a transfer arm having a vacuum line for selectively [vacuum-absorbing] vacuum-suctioning wafers;

a transfer robot for loading and unloading wafers to the processing chambers by moving the transfer arm;

a vertical driving part for vertically moving the transfer robot;

a horizontal driving part for horizontally moving the transfer robot; and

a controller for controlling the transfer robot, the vertical driving part, and the horizontal driving part by applying control signals thereto.

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